



# REPLACEMENT SHEET

ATTY DKT. No.: APPM/007624/PPC/ECP/CKIM

U.S. SERIAL No.: 10/627,154

FILED: JULY 24, 2003

TITLE: STABILIZATION OF ADDITIVES CONCENTRATION IN ELECTROPLATING BATHS FOR INTERCONNECT FORMATION

CONF. No.: 2515

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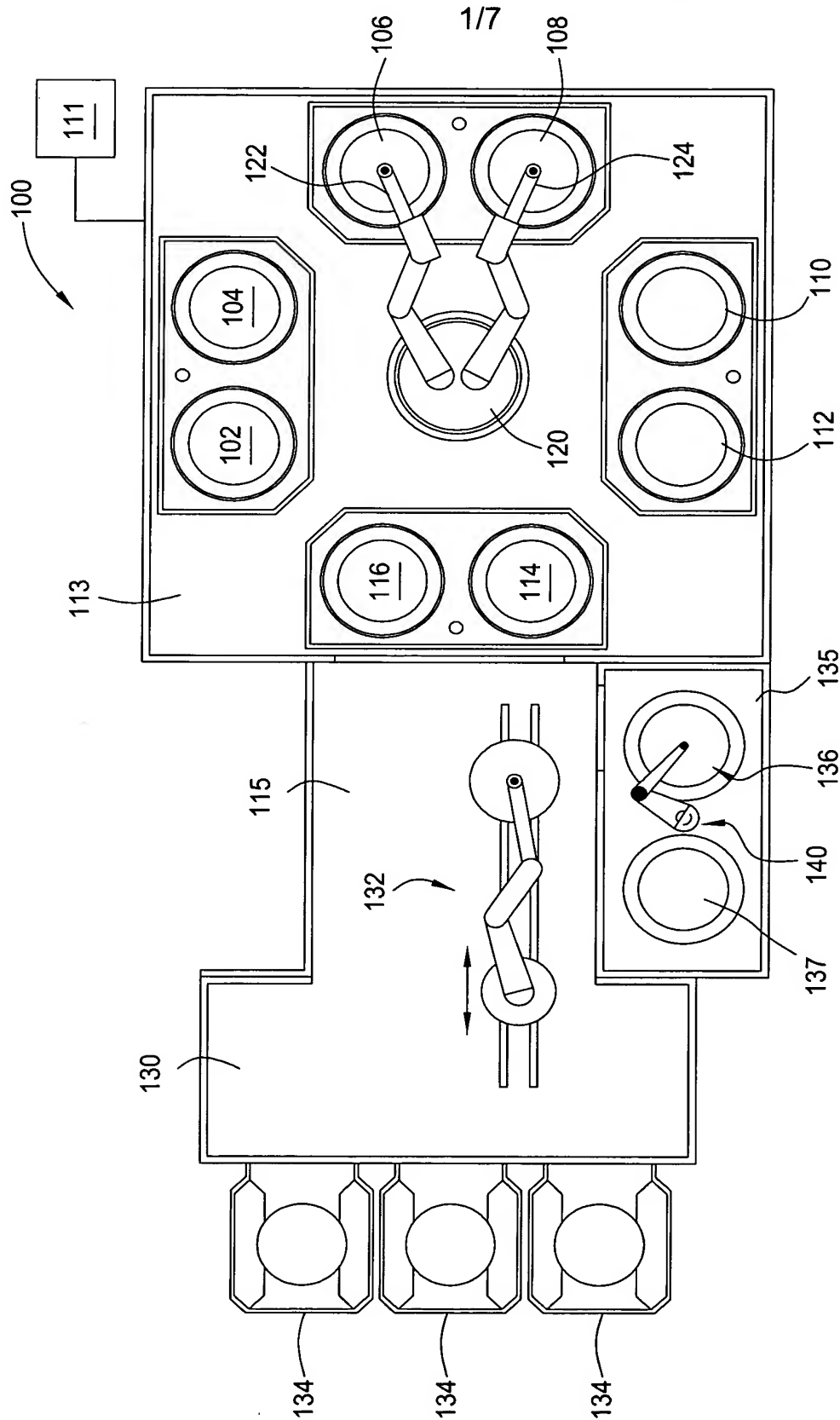


FIG. 1

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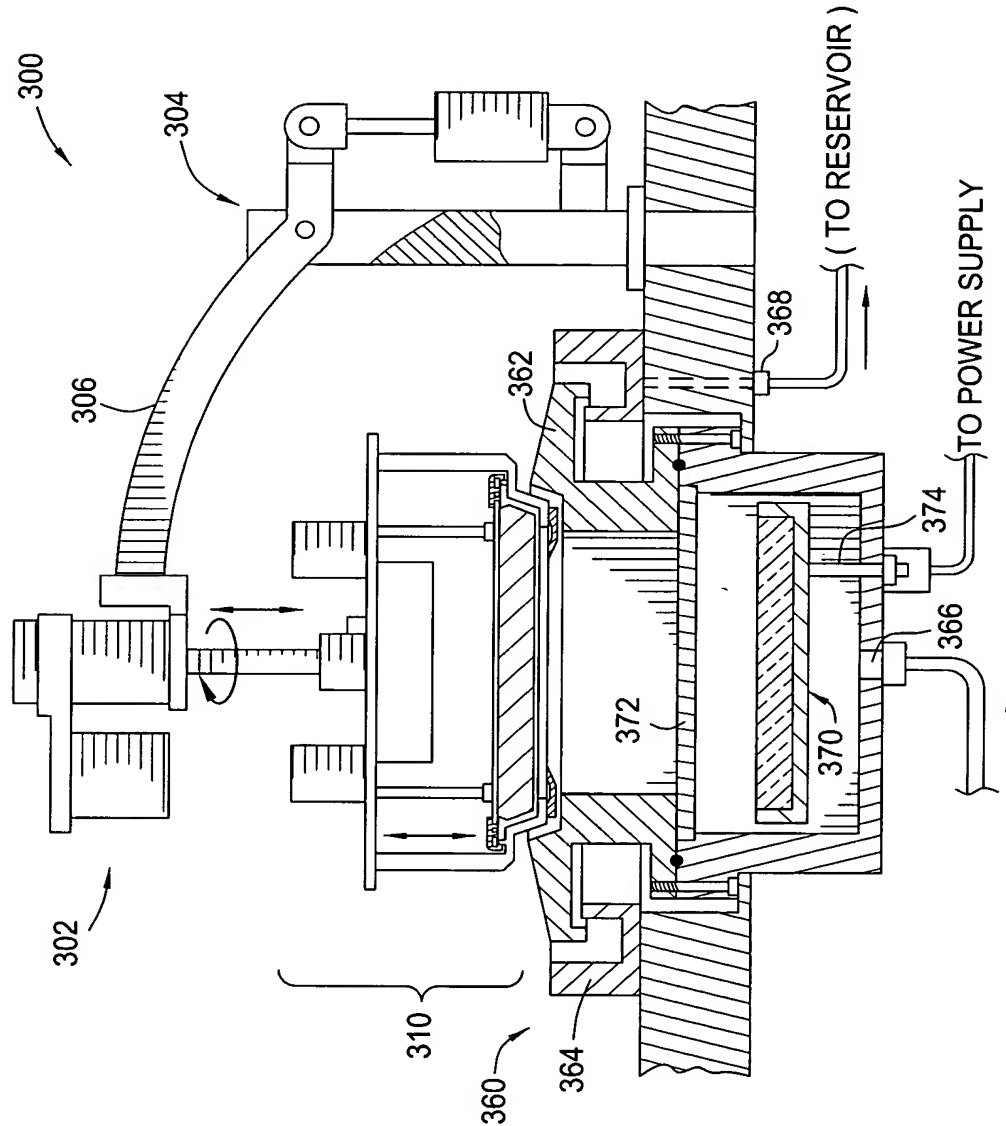


FIG. 3

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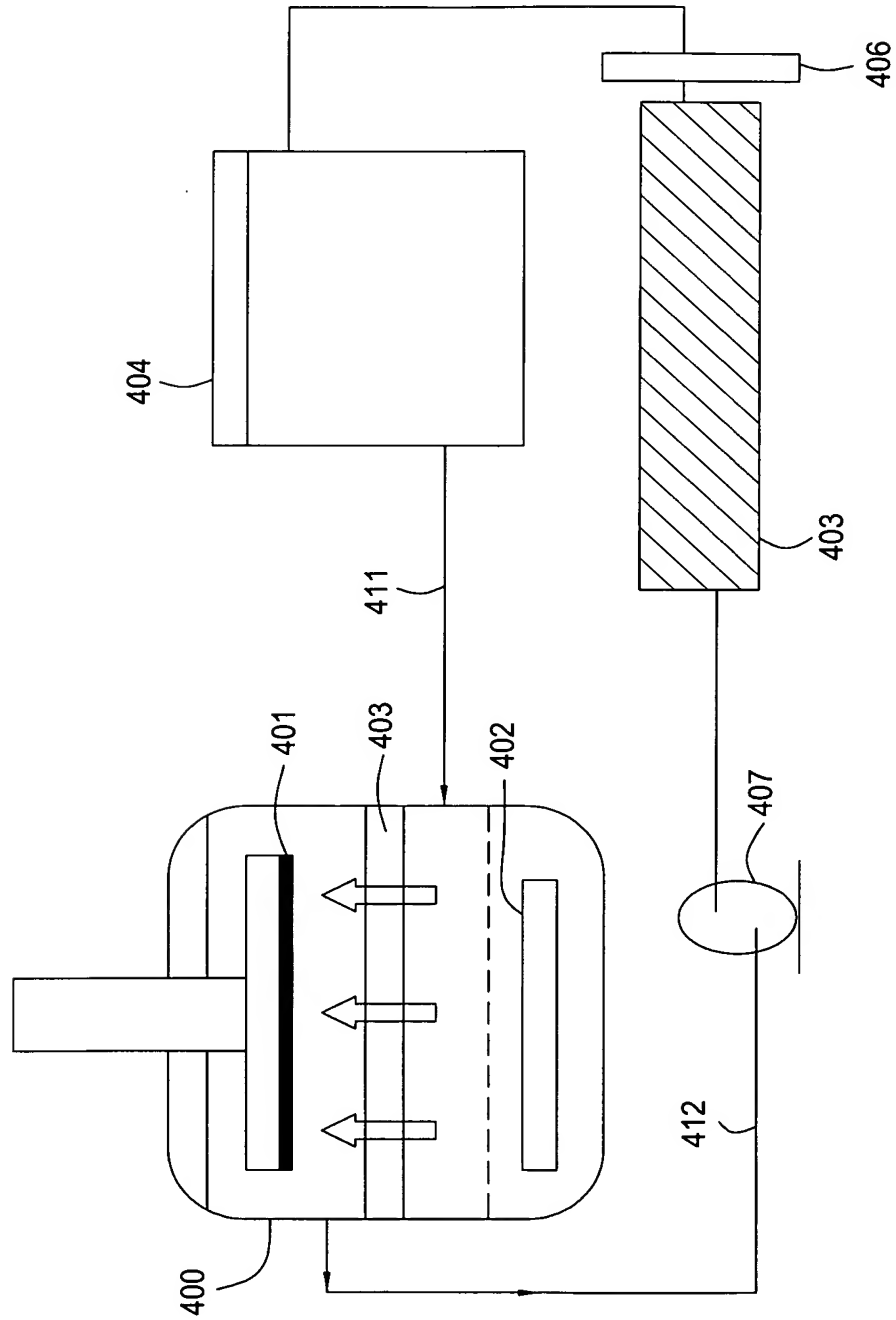
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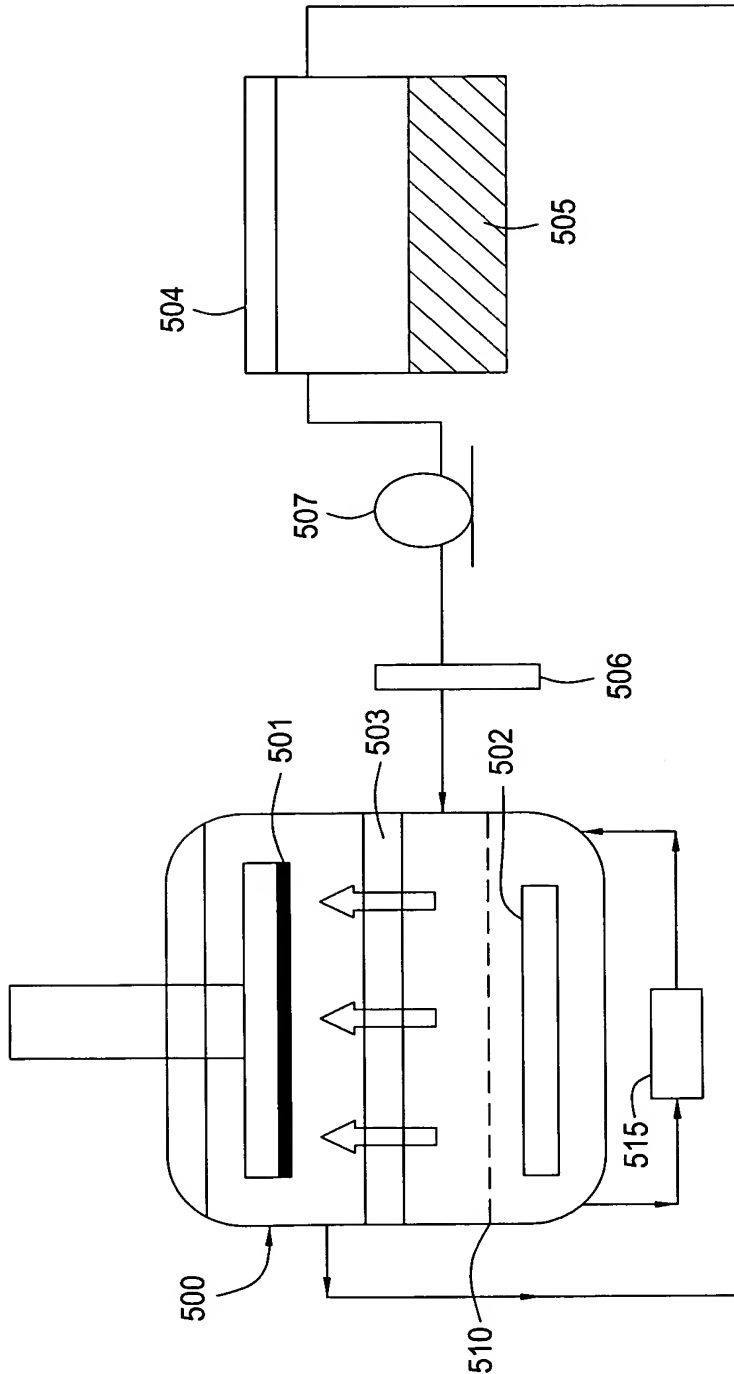


FIG. 5